



CONNECTING INNOVATION™

LEAD FREE SOLDER SOLUTIONS ENVIROMARK 907 NO-CLEAN SOLDER PASTE

EM907 maintains the highest possible activity for a halide-free no-clean formula. EM907 demonstrates a robust printing process with an extended stencil and shelf life. It also maintains excellent solder deposit definition, allowing printing of fine pitch devices without slumping.

Cat. No.	Alloy	Weight	Net Price
EM907 NO-CLEAN, TYPE 3, 89% METALS			
57-3043-9909	Sn96.5 Ag3.0 Cu0.5	500 grams jar	\$57.58
57-3043-9913	Sn96.5 Ag3.0 Cu0.5	600 g cartridge	69.00
57-3043-9915	Sn96.5 Ag3.0 Cu0.5	1000 g cartridge	115.00
57-3043-9916	Sn96.5 Ag3.0 Cu0.5	1400 g cartridge	161.00

R520A WATER-SOLUBLE SOLDER PASTE

R520A Water-Soluble designed to withstand higher temperatures that are needed when soldering lead free alloys. R520A exhibits minimal voiding, long stencil life and tack time while still delivering exceptional solderability to a wide variety of metallic substrates.

Cat. No.	Alloy	Weight	Net Price
R520A WS TYPE 3, 89.5% METAL			
57-3843-8109	Sn96.5 Ag3.0 Cu0.5	500 grams jar	\$57.58
57-3843-8113	Sn96.5 Ag3.0 Cu0.5	600 g cartridge	138.43
57-3843-8115	Sn96.5 Ag3.0 Cu0.5	1000 g cartridge	160.00
57-3843-8116	Sn96.5 Ag3.0 Cu0.5	1400 g cartridge	224.00



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LEAD FREE WAVE SOLDERING FLUXES

Lead-wave and selective soldering require exposing the flux to slightly higher soldering temperatures. Lead Free alloys traditionally wet metal surfaces more slowly than tin-lead. Kester's liquids fluxes for lead-free assembly have new activator packages to enable rapid wetting and hole filling, ensuring reliable product output.

Cat. No.	Description	Weight	Net Price
979 VOC FREE NO-CLEAN			
63-0000-0979	979 VOC Free No-Clean Flux	4 Litres	\$37.42
64-0000-0979	979 VOC Free No-Clean Flux	20 Litres	166.93
65-0000-0979	979 VOC Free No-Clean Flux	200 Liter Drum	1634.29
2220-VF VOC FREE WATER SOLUBLE FLUX			
63-0056-2220	2220-VF VOC Free Water Soluble flux	4 Litres	35.09
64-0056-2220	2220-VF VOC Free Water Soluble flux	20 Litres	188.00
65-0056-2220	2220-VF VOC Free Water Soluble flux	200 Litre Drum	1652.00



LEAD FREE ULTRAPURE BAR SOLDER

Kester's introduced the industry's first distinguishable lead free triangular shape bar, which was designed to reduce any confusion in the customer's production lines when dual production systems are used. Kester's bar is made by a special process, which controls the inclusion of oxides, metallic, and non-metallic impurities, and ensures faster wetting action. The Ultrapure bar is available in tin/copper, tin/silver/copper, and tin/silver alloys.

Cat. No.	Unit	Alloy	Weight	Net Price
LEAD FREE ULTRAPURE BAR				
04-7068-0000	1½ lbs	Sn96.5/Ag3.0/Cu0.5	25 lbs.	\$27.38
04-7012-0000	1½ lbs	Sn99.3/cu0.7	25 lbs.	21.48



275 NO-CLEAN FLUX CORED WIRE SOLDER

Cat. No.	Alloy	Diameter	Net Price
CORE SIZE: 58			
24-7068-7603	Sn96.5/Ag3.0/Cu0.5	.020	\$31.87
24-7068-7617	Sn96.5/Ag3.0/Cu0.5	0.25	25.60
24-7068-7601	Sn96.5/Ag3.0/Cu0.5	.031	21.78
24-7068-7606	Sn96.5/Ag3.0/Cu0.5	.050	22.25
24-7068-7607	Sn96.5/Ag3.0/Cu0.5	.062	21.78

331 WATER SOLUBLE FLUX CORED WIRE SOLDER

Cat. No.	Alloy	Diameter	Net Price
CORE SIZE: 66			
24-7068-6401	Sn96.5/Ag3.0/Cu0.5	.020	\$29.50
24-7068-6417	Sn96.5/Ag3.0/Cu0.5	0.25	25.60
24-7068-6403	Sn96.5/Ag3.0/Cu0.5	.031	29.50
24-7068-6409	Sn96.5/Ag3.0/Cu0.5	.050	22.20
24-7068-6411	Sn96.5/Ag3.0/Cu0.5	.062	21.60



KESTER 256 NO-CLEAN EASY PROFILE SOLDER PASTE

Extremely robust and user-friendly. Can be processed in multitude of different reflow profiles. Highly active and capable of wetting unusual metalisations. Compliant specifications: Bellcore Issue 1 GR-78-CORE, ANSI/J-STD-004 Classification ROL0.

Cat. No.	Alloy	Weight	Net Price
NO-CLEAN, TYPE 3, 90% METAL			
57-3201-4809	Sn63Pb37	500g jar	\$95.00
57-3203-4809	Sn62Pb36Ag2	500g jar	100.71
57-3201-4813	Sn63Pb37	600g cartridge	114.00
57-3203-4813	Sn62Pb36Ag2	600g cartridge	120.86
57-3201-4815	Sn63Pb37	1000g cartridge	160.00
57-3203-4815	Sn62Pb36Ag2	1000g cartridge	171.43
57-3201-4816	Sn63Pb37	1400g cartridge	224.00
57-3203-4816	Sn62Pb36Ag2	1400g cartridge	240.00

KESTER "202" NO-CLEAN PUREMARK SOLDER PASTE

Residues are extremely ICT probe friendly. Excellent print and reflow characteristics for 0201 applications with Type 3 power. Capable of 2 hour break times in printing. High print speeds: up to 8 in/sec. Excellent printing characteristics to 16mil pitch with Type 3 power. High activity on all substrates, including OSPs. Stencil life: 12+ hours (process dependent). Stack tack: 12+ hours. J-STD-004 Flux Classification ROL0. Compliant to Bellcore GR-78-CORE. Compatible with MPM RheoPump™ and DEK ProFlux™ enclosed print head systems.

Cat. No.	Alloy	Weight	Net Price
57-3201-8609	Sn63Pb37	500g jar	\$95.00
57-3203-8609	Sn62Pb36Ag2	500g jar	100.71
57-3201-8613	Sn63Pb37	600g cartridge	114.00
57-3203-8613	Sn62Pb36Ag2	600g cartridge	120.86
57-3201-8615	Sn63Pb37	1000g cartridge	160.00
57-3203-8615	Sn62Pb36Ag2	1000g cartridge	171.43
57-3201-8616	Sn63Pb37	1400g cartridge	224.00
57-3203-8616	Sn62Pb36Ag2	1400g cartridge	240.00

KESTER R562 WATER-SOLUBLE SOLDER PASTE

Kester R562 is an organic acid, water-soluble solder paste specifically designed for resistance to environmental extremes. Water-soluble pastes tend to dry out in low relative humidities and slump at high relative humidities. R562 will maintain its print characteristics, tack and activity even after exposure to environmental extremes. Classified as ORH0 per ANSI-J-STD-004.

Cat. No.	Alloy	Weight	Net Price
57-3201-7509	Sn63Pb37	500g jar	\$95.00
57-3203-7509	Sn62Pb36Ag02	500g jar	100.71
57-3201-7513	Sn63Pb37	600g cartridge	114.00
57-3203-7513	Sn62Pb36Ag02	600g cartridge	120.86
57-3201-7515	Sn63Pb37	1000g cartridge	160.00
57-3203-7515	Sn62Pb36Ag02	1000g cartridge	171.43
57-3201-7516	Sn63Pb37	1400g cartridge	224.00
57-3203-7516	Sn62Pb36Ag02	1400g cartridge	240.00

KESTER "531" WATER-SOLUBLE HYDROMARK SOLDER PASTE

Designed as an all-purpose water-soluble paste, Hydro Mark 531 provides consistent hours of stable stencil life, tack time, and printing characteristics. Offers improved anti-slump characteristics along with excellent solderability to a wide range of surface and component lead metallizations, solving problems caused by slumping, bridging, and wetting. Compliant specifications: ANSI/J-STD-004 Classification ORMO. Residue removal with de-ionized or soft tap water at 120 to 140°F.

Cat. No.	Alloy	Weight	Net Price
57-3201-8509	Sn63Pb37	500g jar	\$95.00
57-3203-8509	Sn62Pb36Ag2	500g jar	100.71
57-3201-8513	Sn63Pb37	600g cartridge	114.00
57-3203-8513	Sn62Pb36Ag2	600g cartridge	120.86
57-3201-8515	Sn63Pb37	1000g cartridge	160.00
57-3203-8515	Sn62Pb36Ag2	1000g cartridge	171.43
57-3201-8516	Sn63Pb37	1400g cartridge	209.06
57-3203-8516	Sn62Pb36Ag2	1400g cartridge	240.00

KESTER R276 NO-CLEAN SYRINGE DISPENSABLE SOLDER PASTE

Provides optimal performance in all types of dispensing applications. R276 is packaged void-free to ensure consistent dispensing in high speed automated processes. Exhibits excellent dispensing characteristics with a wide range of needle diameters. Compliant specifications: Bellcore Issue 1 GR-78-CORE, ANSI/J-STD-004. Classification ROL0.

Cat. No.	Alloy	Weight	Net Price
TYPE 3, 87% METAL			
57-3901-5403	Sn63Pb37	35g syringe	\$17.50
57-3903-5403	Sn62Pb36Ag2	35g syringe	32.15
57-3901-5407	Sn63Pb37	100g syringe	40.00
57-3903-5407	Sn62Pb36Ag2	100g syringe	77.43

KESTER R500 WATER-SOLUBLE SYRINGE DISPENSABLE SOLDER PASTE

The activator package in this formula is aggressive enough to remove tenacious oxide layers or solder to OSP coated boards. R500 delivers excellent wetting characteristics. Compliant specifications: ANSI/J-STD-004 Classification ROL0. Residue removal with de-ionized or soft tap water at 130 to 150 degrees F.

Cat. No.	Alloy	Weight	Net Price
TYPE 3, 87% METAL			
57-3901-5603	Sn63Pb37	35g syringe	\$17.50
57-3903-5603	Sn62Pb36Ag2	35g syringe	32.15
57-3901-5607	Sn63Pb37	100g syringe	40.00
57-3903-5607	Sn62Pb36Ag2	100g syringe	77.43

THE FULLY ACTIVATED ROSIN FLUXES (TYPE RA) FORMULA NO. 1544

This flux may be regarded as the most active of the non-corrosive and non-conductive rosin type fluxes, even when used on the most delicate of electrical or electronic assemblies. Fungus resistant, non-tacky residue. Contains 50% solids.

Cat. No.	Litres	Net Price
63-0000-1544	4	\$34.69

THINNER FORMULA 104

For thinning or replacing evaporation loss of the 1544 and 1571 resin fluxes.

Cat. No.	Litres	Net Price
63-0000-0104	4	\$30.00

KESTER 2235 WATER-SOLUBLE SOLDERING FLUXES

No. 2235 Organic Water-Soluble flux, very active foaming flux for Surface Mount assemblies, designed to help reduce skips on bottom side of SMT pads. Residue removal is required. Use soft or de-ionized water at a temperature of 120 to 150 degrees F. Use 4662 Thinner to maintain correct level of flux activity.

Cat. No.	Litres	Net Price
63-0000-2235	4	\$42.80
64-0000-2235	20	205.71
65-0000-2235	200	1776.00